



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Lloyd G. Burrell et al.

Serial No.: 09/805,027

Group Art Unit: 2822

Filed: March 12, 2001

Examiner: M. Lewis

For: COPPER TO ALUMINUM INTERLAYER INTERCONNECT USING  
STUD AND VIA LINER

*entered by RCE  
filed 8/28/05  
Shaw 8/30/05*

Commissioner for Patents  
United States Patent and Trademark Office  
P. O. Box 1450  
Alexandria, Virginia 22313-1450

SUPPLEMENTAL AMENDMENT UNDER 37 C. F. R. §1.116

Sir:

In response to the Office Action mailed April 20, 2005, and replacing the unentered amendment filed June 20, 2005, please amend the above-identified application as follows (referenced to the amendment filed December 10, 2004):

No amendments to the specification are  
presented in this paper.

Amendments to the claims begin on page 2 of  
this paper.

Remarks begin on page 5 of this paper.

**BOX "AF"**  
**RESPONSE UNDER 37 C.F.R. § 1.116**  
**---EXPEDITE PROCEDURE---**  
**EXAMINING GROUP 2822**